12500 TI Boulevard, MS 8640, Dallas, Texas 75243

PCN# 20251215001.1
Qualification of TI Clark as an additional Assembly site for select devices
Change Notification / Sample Request

Date: December 15, 2025
To: MOUSER PCN

Dear Customer:

This is an announcement of a change to a device that is currently offered by Texas Instruments. The details of this change are on the following pages.

Texas Instruments requires acknowledgement of receipt of this notification within 60 days of the date of this notice. Lack of acknowledgement of this notice within 60 days constitutes acceptance and approval of this change. If samples or additional data are required, requests must be received within 60 days of this notification.

The changes discussed within this PCN will not take effect any earlier than the proposed first ship date on Page 3 of this notification, unless customer agreement has been reached on an earlier implementation of the change.

This notice does not change the end-of-life status of any product. Should product affected be on a previously issued product withdrawal/discontinuance notice, this notification does not extend the life of that product or change the life time buy offering/discontinuance plan.

For questions regarding this notice or to provide acknowledgement of this PCN, you may contact your local Field Sales Representative or the change management team.

For sample requests or sample related questions, contact your local Field Sales Representative.

TI values customer engagement and feedback related to TI changes. Customers should contact TI if there are questions or concerns regarding a change notification.

Change Management Team
SC Business Services

20251215001.1
Attachment

Products Affected:

The devices listed on this page are a subset of the complete list of affected devices. According to our records, you have recently purchased these devices. The corresponding customer part number is also listed, if available.

DEVICE	CUSTOMER PART NUMBER
TPS22964C2YZPR	NULL
TPS274160ARLHR	NULL

Technical details of this Product Change follow on the next page(s).

PCN Number:	20251215001.1	**PCN Date:**	December 15, 2025
Title:	Qualification of TI Clark as an additional Assembly site for devices		
Customer Contact:	Change Management Team	**Dept:**	Quality Services
Proposed 1st Ship Date:	March 15, 2026	**Sample requests accepted until:**	February 13, 2026*

***Sample requests received after February 13, 2026 will not be supported.**

Change Type:

☒	Assembly Site	☐	Design	☐	Wafer Bump Material
☐	Assembly Process	☐	Data Sheet	☐	Wafer Bump Process
☐	Assembly Materials	☐	Part number change	☐	Wafer Fab Site
☐	Mechanical Specification	☐	Test Site	☐	Wafer Fab Material
☒	Packing/Shipping/Labeling	☐	Test Process	☐	Wafer Fab Process

PCN Details

Description of Change:

Texas Instruments is pleased to announce the addition of TI Clark as an additional Assembly site for the device listed below. No material differences between sites.

Qual details are provided in the Qual Data Section.

Reason for Change:

Supply continuity

Anticipated impact on Form, Fit, Function, Quality or Reliability (positive / negative):

Review the standard data packet (SDP) for comparison.

Impact on Environmental Ratings:

Checked boxes indicate the status of environmental ratings following implementation of this change. If below boxes are checked, there are no changes to the associated environmental ratings.

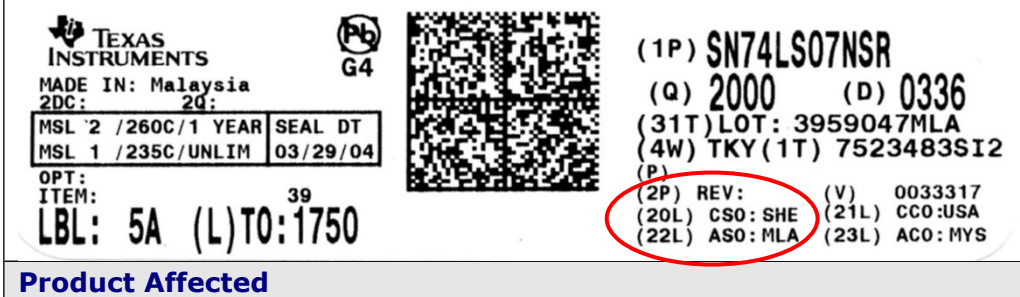
RoHS	REACH	Green Status	IEC 62474
☒ No Change	☒ No Change	☒ No Change	☒ No Change

Changes to product identification resulting from this PCN:

Assembly Site Information:

Assembly Site	Assembly Site Origin Code (22L)	Assembly Site Country Code (23L)	Assembly Site City
CDAT	CDA	CHN	Chengdu
Clark	**QAB**	**PHL**	**Angeles City, Pampanga**

Sample product shipping label (not actual product label):



Product Affected

TPS22964C2YZPR	TPS274160ARLHR

Qualification Report

TPS274160ARLHR RFAB LBC8 CDAT offload to Clark

Approve Date 14-October-2025

Qualification Results

Data Displayed as: Number of lots / Total sample size / Total failed

Type	#	Test Name	Condition	Duration	Qual Device: TPS274160ARLHR	QBS Reference: LM70880QRRXRQ1	QBS Reference: DRV3245AQPHPRQ1
HAST	A2	Biased HAST	110C/85%RH	264 Hours	-	-	1/77/0
HAST	A2	Biased HAST	130C/85%RH	96 Hours	-	3/231/0	-
UHAST	A3	Autoclave	121C/15psig	96 Hours	-	-	1/77/0
UHAST	A3	Unbiased HAST	130C/85%RH	96 Hours	-	3/231/0	-
TC	A4	Temperature Cycle	-65C/150C	500 Cycles	3/231/0	3/231/0	1/77/0
HTSL	A6	High Temperature Storage Life	150C	1000 Hours	-	3/135/0	-
HTSL	A6	High Temperature Storage Life	175C	500 Hours	-	-	1/45/0
HTOL	B1	Life Test	125C	1000 Hours	-	3/231/0	1/77/0
ELFR	B2	Early Life Failure Rate	125C	48 Hours	-	3/2400/0	1/800/0
SD	C3	PB-Free Solderability	Precondition w.155C Dry Bake (4 hrs +/- 15 minutes)	-	-	1/15/0	-
PD	C4	Physical Dimensions	Cpk>1.67	-	-	3/30/0	-
ESD	E2	ESD CDM	-	500 Volts	-	1/3/0	1/3/0
ESD	E2	ESD CDM	-	750 Volts	-	-	1/3/0
ESD	E2	ESD HBM	-	2000 Volts	-	1/3/0	-
ESD	E2	ESD HBM	-	4000 Volts	-	-	1/3/0
LU	E4	Latch-Up	Per JESD78	-	-	1/3/0	1/6/0
CHAR	E5	Electrical Distributions	Cpk>1.67 Room, hot, and cold	-	-	3/90/0	3/90/0

QBS: Qual By Similarity, also known as Generic Data
Qual Device TPS274160ARLHR is qualified at MSL2 260C
Preconditioning was performed for Autoclave, Unbiased HAST, THB/Biased HAST, Temperature Cycle, Thermal Shock, and HTSL, as applicable
The following are equivalent HTOL options based on an activation energy of 0.7eV : 125C/1k Hours, 140C/480 Hours, 150C/300 Hours, and 155C/240 Hours
The following are equivalent HTSL options based on an activation energy of 0.7eV : 150C/1k Hours, and 170C/420 Hours
The following are equivalent Temp Cycle options per JESD47 : -55C/125C/700 Cycles and -65C/150C/500 Cycles
Quality and Environmental data is available at TI's external Web site: http://www.ti.com/
TI Qualification ID: R-CHG-2502-037

Qualification Report

TPS22964CYZPR in RFAB/TI-Clark

Approve Date 08-MARCH -2023

Qualification Results

Data Displayed as: Number of lots / Total sample size / Total failed

Type	#	Test Name	Condition	Duration	Qual Device: TPS22964CYZPR	QBS Reference: TLV7081YKAR	QBS Reference: TPA6140A2YFFR	QBS Reference: BQ25118AYFPR
HAST	A2	Biased HAST	130C/85%RH	96 Hours	-	3/231/0	-	3/231/0
UHAST	A3	Autoclave	121C/15psig	96 Hours	-	-	-	-
UHAST	A3	Unbiased HAST	130C/85%RH	96 Hours	-	3/231/0	3/231/0	3/231/0
TC	A4	Temperature Cycle	-40C/125C	850 Cycles	-	3/231/0	-	-
TC	A4	Temperature Cycle	-55C/125C	700 Cycles	-	-	3/231/0	3/231/0
TC	A4	Temperature Cycle	-65C/150C	500 Cycles	-	-	-	-
HTSL	A6	High Temperature Storage Life	150C	1000 Hours	-	3/231/0	-	-
HTSL	A6	High Temperature Storage Life	170C	420 Hours	-	-	-	3/231/0
HTOL	B1	Life Test	125C	1000 Hours	-	3/231/0	-	-
HTOL	B1	Life Test	140C	480 Hours	-	-	3/231/0	-
HTOL	B1	Life Test	150C	300 Hours	-	-	-	3/231/0
ELFR	B2	Early Life Failure Rate	125C	48 Hours	-	3/3000/0	-	-
SD	C3	PB-Free Solderability	Precondition w.155C Dry Bake (4 hrs +/- 15 minutes); PB-Free Solder;	-	-	3/66/0	-	-
ESD	E2	ESD CDM	-	500 Volts	1/3/0	3/9/0	-	3/9/0
ESD	E2	ESD CDM	-	750 Volts	-	-	2/6/0	-
ESD	E2	ESD HBM	-	2000 Volts	1/3/0	3/9/0	3/9/0	-
LU	E4	Latch-Up	Per JESD78	-	1/6/0	3/18/0	3/18/0	-
CHAR	E5	Electrical Characterization	Per Datasheet Parameters	-	1/30/0	1/30/0	-	1/30/0

QBS: Qual By Similarity, also known as Generic Data
Qual Device TPS22964CYZPR is qualified at MSL1 260C
Preconditioning was performed for Autoclave, Unbiased HAST, THB/Biased HAST, Temperature Cycle, Thermal Shock, and HTSL, as applicable
The following are equivalent HTOL options based on an activation energy of 0.7eV : 125C/1k Hours, 140C/480 Hours, 150C/300 Hours, and 155C/240 Hours
The following are equivalent HTSL options based on an activation energy of 0.7eV : 150C/1k Hours, and 170C/420 Hours
The following are equivalent Temp Cycle options per JESD47 : -55C/125C/700 Cycles and -65C/150C/500 Cycles
Quality and Environmental data is available at TI's external Web site: http://www.ti.com/
TI Qualification ID: R-BKF-2303-016

In performing change qualifications, Texas Instruments follows integrated circuit industry standards in performing defect mechanism analysis and failure mechanism-based accelerated environmental testing to ensure wafer fab process, assembly process and product quality and reliability. As encouraged by these standards, TI uses both product-specific and generic (family) data in qualifying its changes. For devices to be categorized as a 'product qualification family' for generic data purposes, they must share similar product, wafer fab process and assembly process elements. The applicability of generic data (also known at TI as Qualification by Similarity (QBS)) is determined by the Reliability Engineering function following these industry standards. Generic data is shown in the qualification report in columns titled "QBS Process" (for wafer fab process), "QBS Package" (for assembly process) and "QBS Product" (for product family).

For questions regarding this notice, e-mails can be sent to the Change Management team or your local Field Sales Representative.

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